

描述 / Descriptions

MM 8 9 11

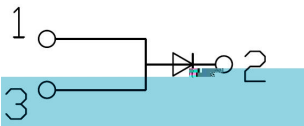
特征 / Features

* b 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37 38 39 40 41 42 43 44 45 46 47 48 49 50 51 52 53 54 55 56 57 58 59 60 61 62 63 64 65 66 67 68 69 70 71 72 73 74 75 76 77 78 79 80 81 82 83 84 85 86 87 88 89 90 91 92 93 94 95 96 97 98 99 100

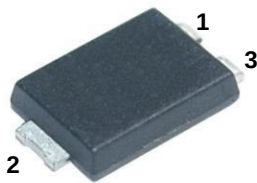
用途 / Applications

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37 38 39 40 41 42 43 44 45 46 47 48 49 50 51 52 53 54 55 56 57 58 59 60 61 62 63 64 65 66 67 68 69 70 71 72 73 74 75 76 77 78 79 80 81 82 83 84 85 86 87 88 89 90 91 92 93 94 95 96 97 98 99 100

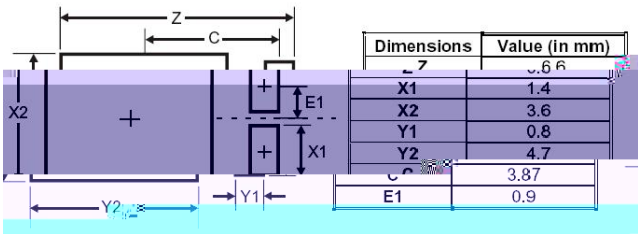
内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



X X X



放大及印章代码 / hFE Classifications & Marking

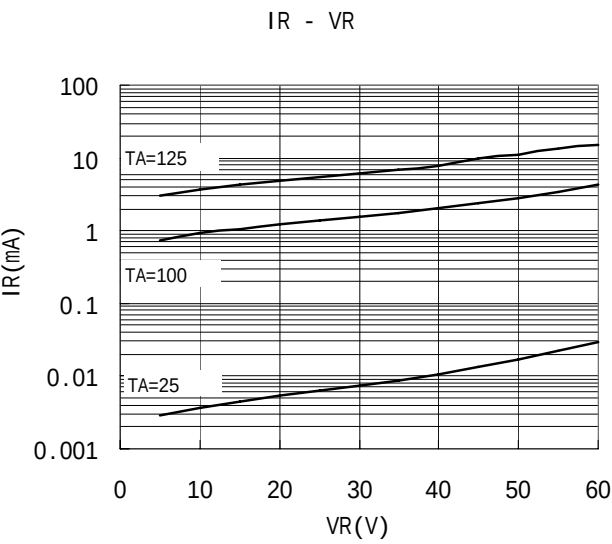
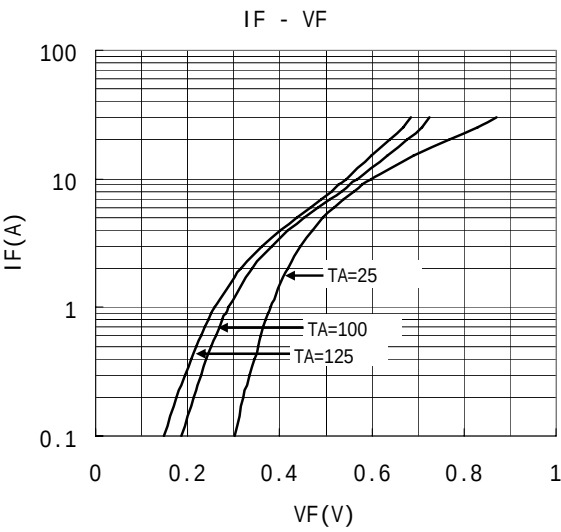
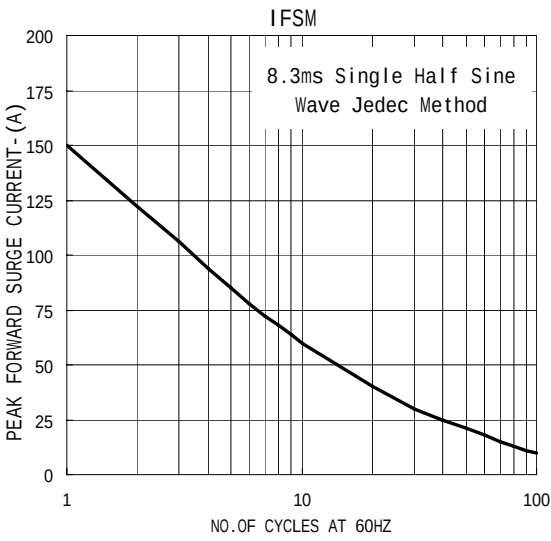
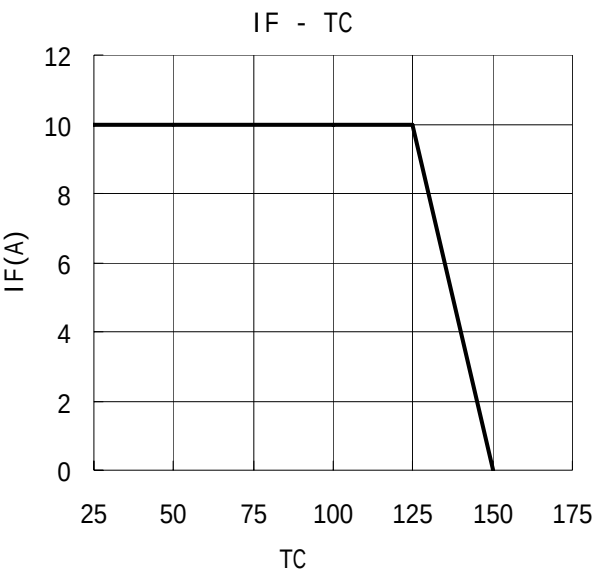
M 1 2

$v^{\prime \Omega}$	y^N	$^{\prime \Omega} \bar{\theta}$	D_H
	θ		

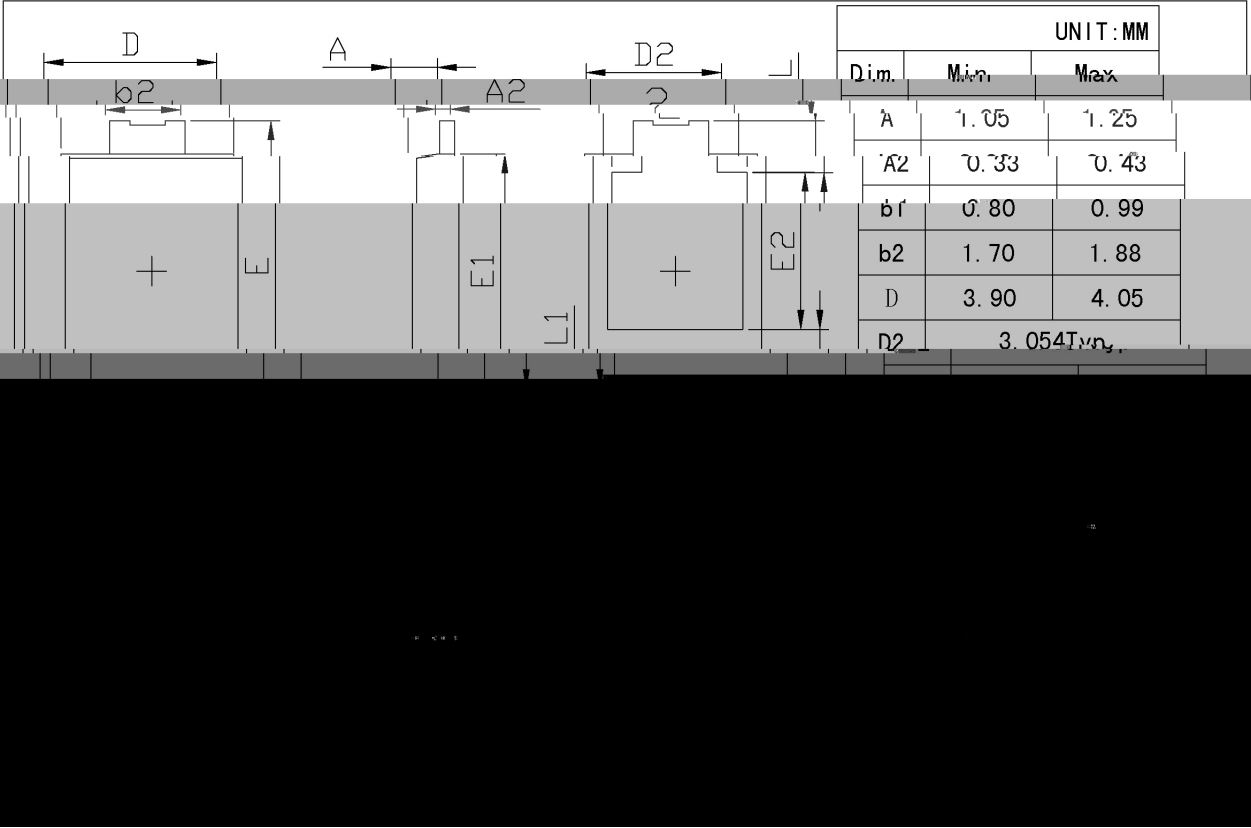
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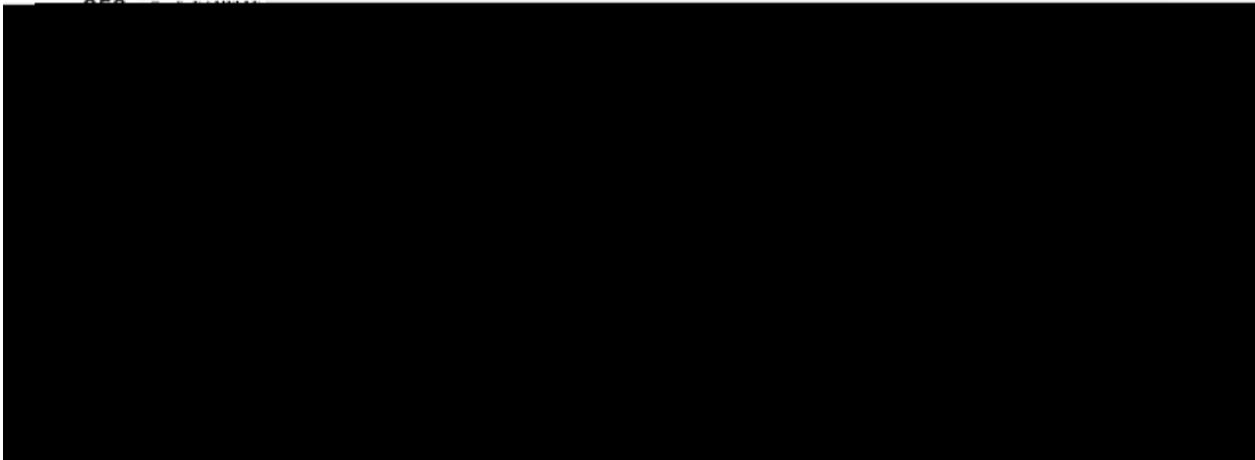
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions



回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



” X
♫ □ ŷ K † i`H K
Š Œ □ ŷ ° † i`H `Y / ⅈ °
i` ⅄, ∅ ŷ ⅈ K †

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

□ ŷ X ° † `H X °

包装规格 / Packaging SPEC.

∩` γ

	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-277	5,000	3	15,000	6	90,000	13 ×12	360×360×50	380×335×366

使用说明 / Notices